

## 1. General description

Planar passivated high commutation three quadrant triac in an ITO220 internally insulated plastic package intended for use in circuits where high static and dynamic  $dV/dt$  and high  $dI/dt$  can occur. This "series B" triac will commute the full RMS current at the maximum rated junction temperature without the aid of a snubber. This device has high  $T_j$  operating capability and an internally isolated mounting base.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ °C}$ )
- High surge capability
- Isolated mounting base with 2500 V (RMS) isolation
- Least sensitive gate for highest noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- Very high immunity to false turn-on by  $dV/dt$

## 3. Applications

- Electronic thermostats (heating and cooling)
- High power motor controls
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

## 4. Quick reference data

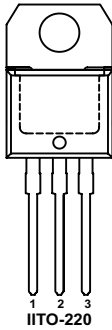
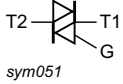
Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
<b>Absolute maximum rating</b>				
$V_{DRM}$	repetitive peak off-state voltage		800	V
$I_{T(RMS)}$	RMS on-state current	square-wave pulse; $T_{mb} \leq 116\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	12	A
$I_{TSM}$	non-repetitive peak forward current	full sine wave; $t_p = 20\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	140	A
		full sine wave; $t_p = 16.7\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$	153	A
$T_j$	junction temperature		150	°C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+$ $T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-$ $T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-$ $T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
$I_H$	holding current	$V_D = 12\text{ V}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 9</a>	-	-	60	mA
$V_T$	on-state voltage	$I_T = 18\text{ A}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 10</a>	-	1.3	1.5	V
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}; T_j = 125\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of $V_{DRM})$ ; exponential waveform; gate open circuit	1000	-	-	V/ $\mu$ s
		$V_{DM} = 536\text{ V}; T_j = 150\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of $V_{DRM})$ ; exponential waveform; gate open circuit	600	-	-	V/ $\mu$ s
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400\text{ V}; T_j = 125\text{ }^\circ\text{C}; I_{T(RMS)} = 12\text{ A};$ $dV_{com}/dt = 20\text{ V}/\mu\text{s};$ gate open circuit; snubberless condition	20	-	-	A/ms
		$V_D = 400\text{ V}; T_j = 150\text{ }^\circ\text{C}; I_{T(RMS)} = 12\text{ A};$ $dV_{com}/dt = 20\text{ V}/\mu\text{s};$ gate open circuit; snubberless condition	8	-	-	A/ms

## 5. Pinning information

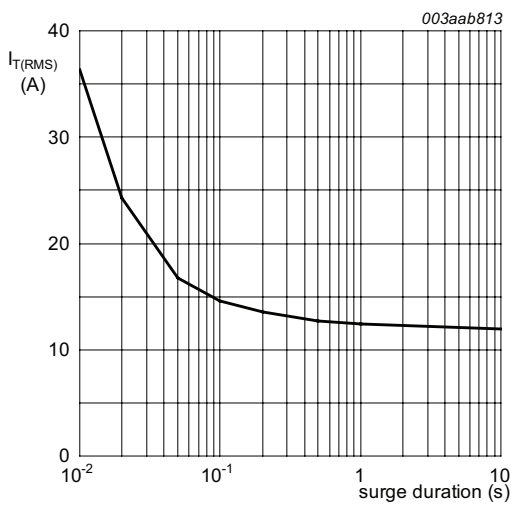
Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	 <p style="text-align: center;">1 2 3 ITO-220</p>	 <p style="text-align: center;">sym051</p>
2	T2	main terminal 2		
3	G	gate		
mb	n.c	mounting base; isolated		

## 8. Limiting values

Table 4. Limiting values

Symbol	Parameter	Conditions	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage		800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 116^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	12	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $t_p = 20\text{ ms}$ ; $T_{j(\text{init})} = 25^{\circ}\text{C}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	140	A
		full sine wave; $t_p = 16.7\text{ ms}$ ; $T_{j(\text{init})} = 25^{\circ}\text{C}$	153	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ms}$ ; sine wave	98	$\text{A}^2/\text{s}$
$di_T/dt$	rate of rise of on-state current	$I_G = 100\text{mA}$	100	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current		2	A
$P_{GM}$	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
$T_{stg}$	storage temperature		-40 to 150	$^{\circ}\text{C}$
$T_j$	junction temperature		150	$^{\circ}\text{C}$



$f = 50\text{Hz}$ ;  $T_{mb} = 116^{\circ}\text{C}$

Fig. 1. RMS on-state current as a function of surge duration; maximum values

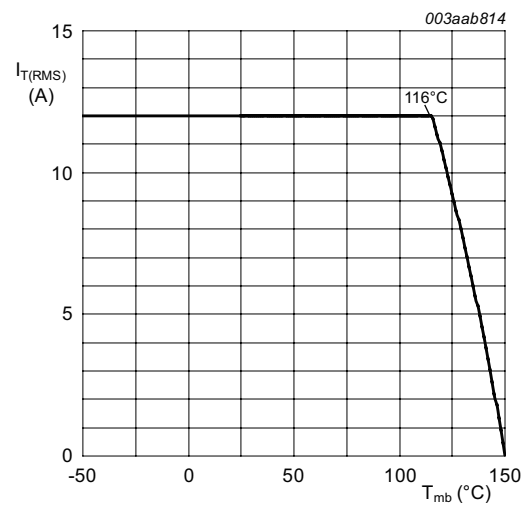
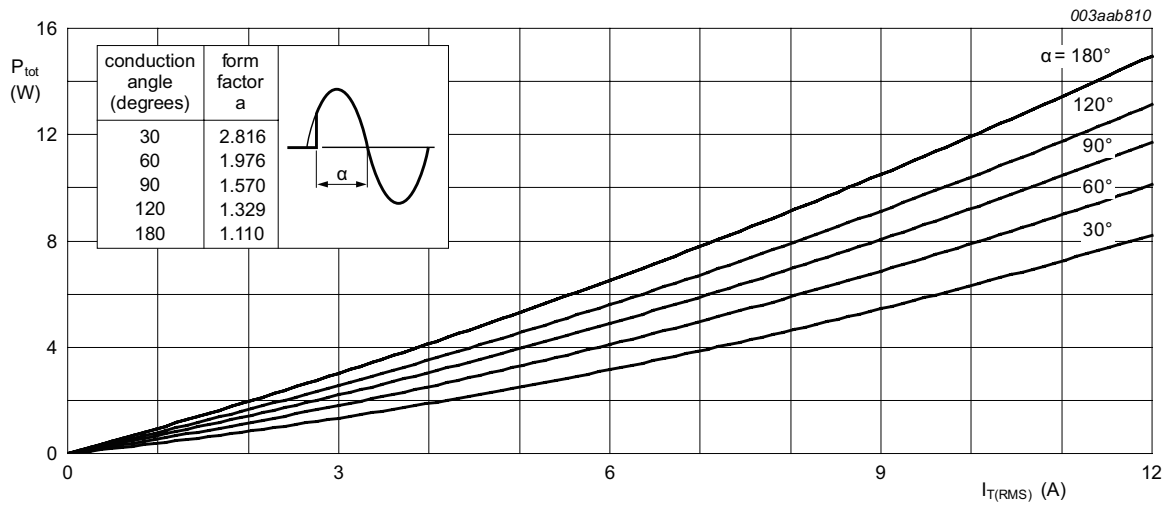
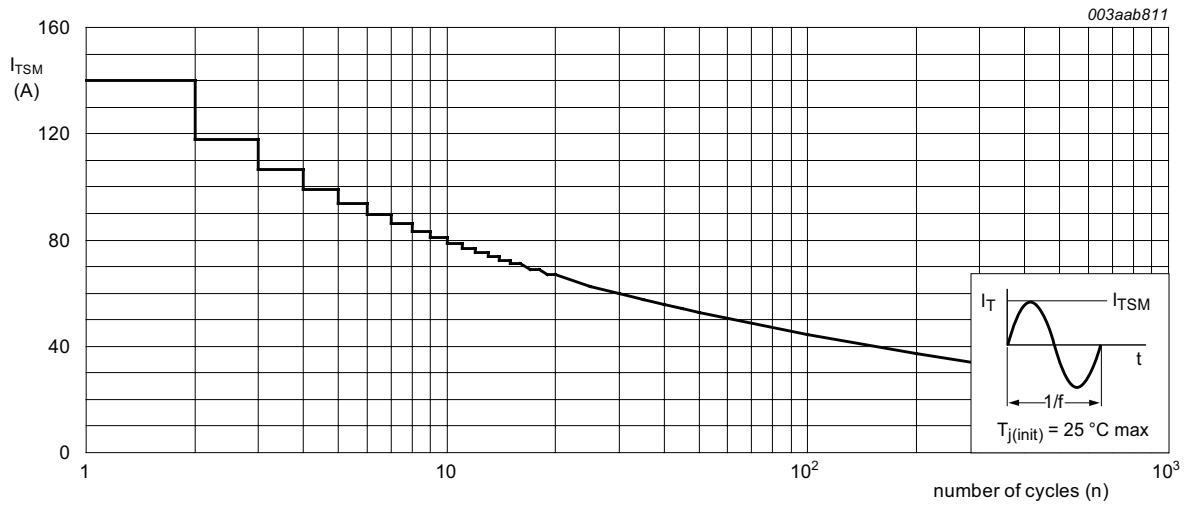


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



$\alpha$  = conduction angle  
 $a$  = form factor =  $I_{T(RMS)} / I_{T(AV)}$

**Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values**



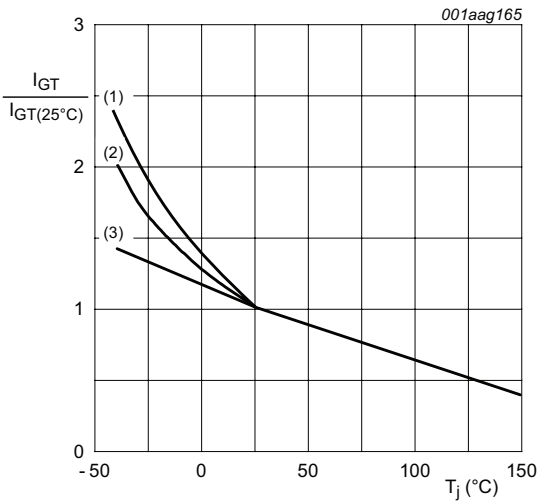
$f = 50$  Hz

**Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values**

## 11. Characteristics

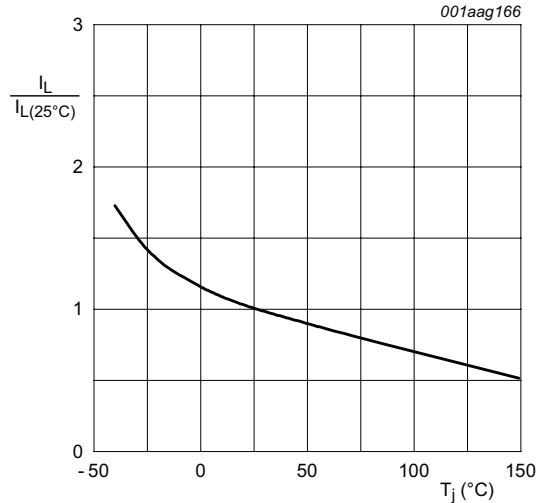
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	2	-	50	mA
$I_L$	latching current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 8</a>	-	-	60	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 8</a>	-	-	90	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-;$ $T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 8</a>	-	-	60	mA
$I_H$	holding current	$V_D = 12\text{ V}; T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 9</a>	-	-	60	mA
$V_T$	on-state voltage	$I_T = 18\text{ A}; T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 10</a>	-	1.3	1.5	V
$V_{GT}$	gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_J = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>	-	0.8	1	V
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_J = 150\text{ }^\circ\text{C}$	0.25	0.4	-	V
$I_D$	off-state current	$V_D = 800\text{ V}; T_J = 125\text{ }^\circ\text{C}$	-	0.1	0.5	$\mu\text{A}$
		$V_D = 800\text{ V}; T_J = 150\text{ }^\circ\text{C}$	-	0.4	2	mA
<b>Dynamic characteristics</b>						
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}; T_J = 125\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of $V_{DRM});$ exponential waveform; gate open circuit	1000	-	-	V/ $\mu\text{s}$
		$V_{DM} = 536\text{ V}; T_J = 150\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of $V_{DRM});$ exponential waveform; gate open circuit	600	-	-	V/ $\mu\text{s}$
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400\text{ V}; T_J = 125\text{ }^\circ\text{C}; I_{T(RMS)} = 12\text{ A};$ $dV_{com}/dt = 20\text{ V}/\mu\text{s};$ gate open circuit; snubberless condition	20	-	-	A/ms
		$V_D = 400\text{ V}; T_J = 150\text{ }^\circ\text{C}; I_{T(RMS)} = 12\text{ A};$ $dV_{com}/dt = 20\text{ V}/\mu\text{s};$ gate open circuit; snubberless condition	8	-	-	A/ms

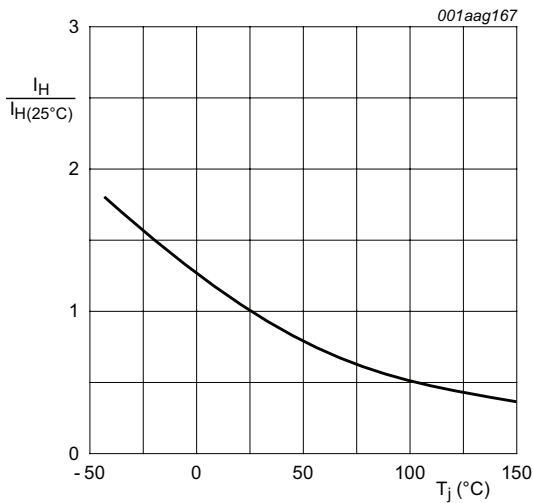


- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

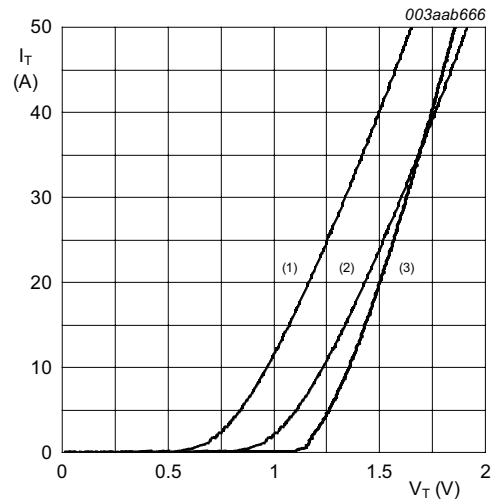
**Fig. 7. Normalized gate trigger current as a function of junction temperature**



**Fig. 8. Normalized latching current as a function of junction temperature**



**Fig. 9. Normalized holding current as a function of junction temperature**



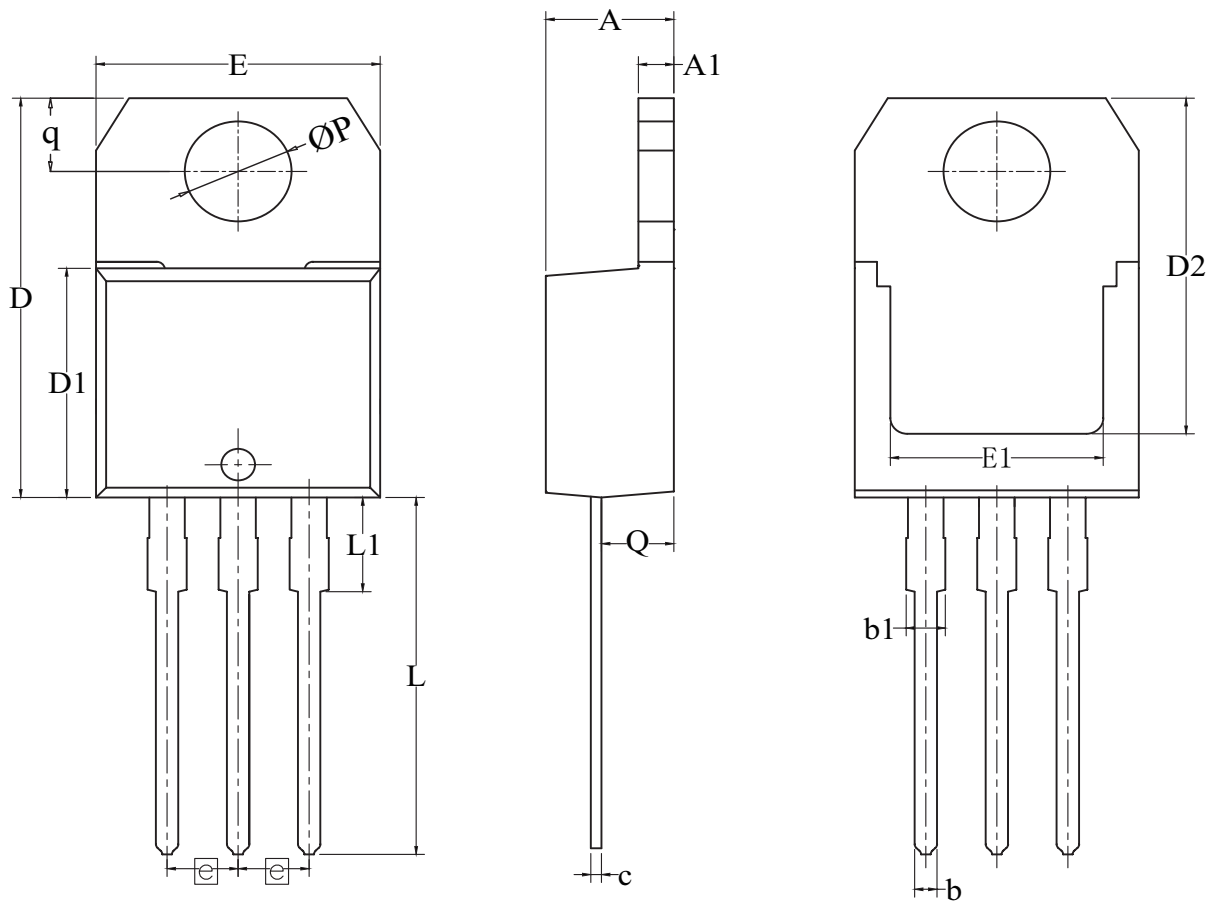
- $V_o = 1.024 \text{ V}; R_s = 0.021 \Omega$
- (1)  $T_j = 125^\circ\text{C}$ ; typical values
  - (2)  $T_j = 125^\circ\text{C}$ ; maximum values
  - (3)  $T_j = 25^\circ\text{C}$ ; maximum values

**Fig. 10. On-state current as a function of on-state voltage**

## 12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 leads TO-220

IITO220



Unit	A	A1	b	b1	c	D	D1	D2	E	E1	e	L	L1	P	Q	q
MM	min	4.30	1.25	0.69	1.20	0.40	15.20	8.50	12.20	10.00	6.86	12.80	2.70	3.70	2.40	2.70
	max	4.70	1.40	0.90	1.72	0.60	16.00	9.02	12.88	10.40	8.89	2.54 (BSC)	14.00	3.30	3.95	2.80

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